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E-tec Sockets for SEMPAC packages

E-tec is currently cooperating with SEMPAC, a US based manufacturer of “air-cavity” packages marketed under the tradename « Open-Pak™ ». These packages represent an ideal solution for quick turn assembly, customer samples, integrated circuit die qualifications, device prototyping and small lot engineering and/or assembly build requirements. E-tec sockets are adapted to these SEMPAC packages and they can incorporate additional custom specific socket requirements (size limitations, open top die access, etc) to help customers during the prototyping phase.

The notable key advantages for utilizing SEMPAC's “air-cavity” packages can be witnessed in the quick turn, cost effective alternative to high priced ceramic versions and superior and/or equal performance to transfer-molded packages.

SEMPAC’s “Open-Pak”™ packages meet the latest JEDEC outline & footprint standards and are available in QFN, QFP, SOIC and SSOP architectures, which in combination with the E-tec socketing solutions offer an additional design flexibility to the customers.

For further information on SEMPAC please visit : www.sempac.com